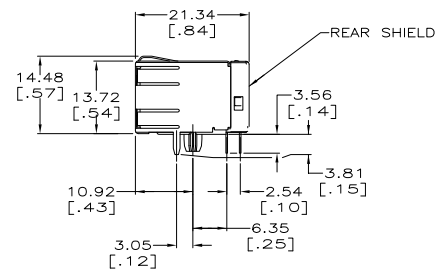
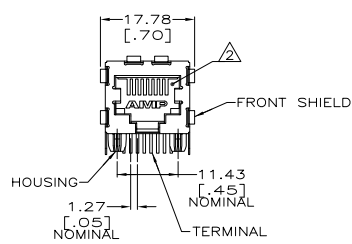


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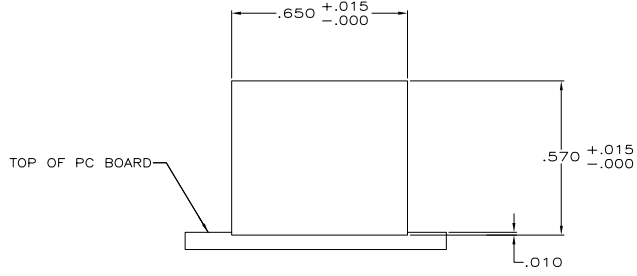
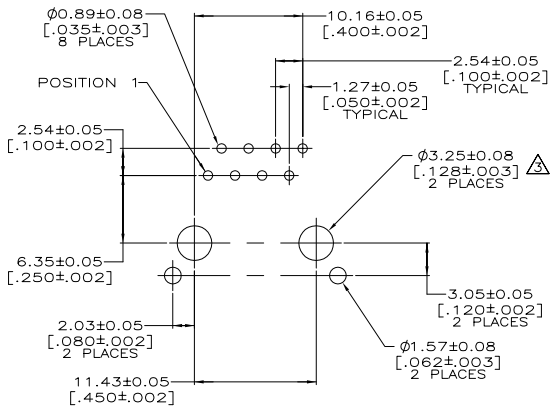
LOC		DST		REVISIONS			
P	UR	DESCRIPTION	DATE	DR	APPD	TY	SY
B1		REV PER ECR-09-004284	16APR2009				



1 MATERIAL: HOUSING - NYLON, BLACK, IR REFLOW COMPATIBLE, UL 94V-0.
 TERMINALS - 0.33[.013] THICK PHOS BRONZE PLATED WITH 1.27μm[.000050] MINIMUM THICK HARD GOLD IN LOCALIZED AREA AND 3.81μm [0.00150] MINIMUM THICK MATTE TIN IN SOLDER AREA OVER 1.27μm[.000050] MINIMUM THICK NICKEL UNDERPLATE.
 SHIELDS - 0.25[.010] THICK COPPER ALLOY PLATED WITH 1.27μm[.000050] MINIMUM NICKEL AND 2.03μm [0.00080] MINIMUM HOT TIN DIP ON PCB GROUND TABS.

⚠ JACK CAVITY CONFORMS TO FCC RULES AND REGULATIONS, PART 68 SUBPART F.

⚠ USE #30 DRILL BIT OR 3.25mm DRILL BIT WHEN PRODUCING THESE PCB HOLES.



SUGGESTED PANEL CUTOUT
 SCALE 4:1

SUGGESTED PC BOARD LAYOUT
 COMPONENT SIDE (TOP)
 SCALE 4:1

5406295-1
 PART NUMBER

THIS DRAWING IS A CONTROLLED DOCUMENT.		DR: J. SPRINKLE / A. MAYER	DATE: 01JAN2005	Tyco Electronics Corporation Harrisburg, Pa 17105-3608
DIMENSIONS: mm		DR: J. WESTMAN	DATE: 01JAN2005	
TOLERANCES UNLESS OTHERWISE SPECIFIED:		DESIGNER: S. SLEICKINGER	DATE: 01JAN2005	Tyco Electronics
0 P/C # -		PRODUCT SPEC: 108-1163	NAME: MODULAR JACK ASSEMBLY, SINGLE PORT, 8 POSITION, SHIELDED, REVERSE PANEL GROUND TABS, CATEGORY 4	
1 P/C # ±.02[.01]		APPLICATION SPEC: 114-2048	SEE CASE CODE (FORMING NO): A200779	RESTRICTED TO
2 P/C # ±.013[.005]		WEIGHT: -	SCALE: 2:1	
3 P/C # ±.013[.005]		FINISH: -	SHEET: 1 of 1	REV: B1
4 P/C # -		CUSTOMER DRAWING	SCALE: 2:1	